

Trusted Packaging / Assembly Services

Fact Sheet

October 2010

www.aeroflex.com/Trusted



TRUSTED ACCREDITATION

Aeroflex Plainview received Category 1A Trusted Accreditation by the Defense Microelectronics Activity as a Microelectronics Trusted Source for DoD and all other U.S. government users. The scope of accreditation is for Packaging /Assembly.

Aeroflex Plainview for over thirty-five years has been a leader in the Microelectronic packaging arena. We are well experienced in Chip-On-Board (COB), Chip and Wire, Surface Mount Technology (SMT), and Multi-Chip-Module (MCM) technology. All designed to operate in severe environments where performance, size and weight are the upmost critical parameters.

Aeroflex Plainview offers:

- One stop solution for your microelectronic assembly, evaluation, test and screening requirements
- Quick-turn capabilities available
- MIL-PRF-38534 compliant (Class H &K), ISO-9001-2000 and AS9100 certified
- Element evaluation and component screening
- Full turnkey and "design-to-spec" programs available
- Value-added services such as radiation testing, classified testing and COTS/commercial up screening
- Class 100,000 clean rooms for hybrid, SMT and box assembly
- Class 10,000 for thick film substrate manufacturing

PACKAGING / ASSEMBLY CAPABILITIES

- Wafer saw and electrical probe
- State-of-the Art gold ball bonding: 60 μ pitch available
- Large Area - 16" x 13" bondable area
- 1 mil to 2 mil automatic gold ball bonding
- Gold and aluminum wedge bonding
- Heavy Aluminum - 4 mil to 20 mil wire
- Ribbon Bonding - 0.25 mil x 3 mil to 2 mil x 10 mil
- Vacuum brazing - Eutectic die and substrate attach
- Epoxy die bonding to 12 μ placement accuracy

- Gap welding - beam lead diodes / wire / ribbon
- Active laser trim of thick and thin film resistors
- RF /Microwave tuning
- Hi-Rel Chip-On-Board assemblies / SMT
- Hermetic or epoxy package sealing
- Plastic packages / flip chips
- Transformers / coils
- Internal preseat visual
 - MIL-STD-883, method 2010 or 2017, Condition A or B
- Hermetic packages available
 - LCC, PGA, QFP, DIP, FP, TO cans, ring frame, Multi-Chip Modules (MCM)
- Solder dip - MIL-STD-883, method 2003

In addition to the Category 1A Trusted Accreditation, Aeroflex Plainview is proud to offer:

- Electrical test
 - Wafer level DC parametrics, memory, logic and analog IC testing, wafer probe and package IC testing, RF testing to 40GHz
- Burn-In Services
 - Static/Dynamic burn-in, Accelerated life test
- Environmental test per MIL-STD-883 test methods
 - Hermeticity - method 1014, condition A1, A2, C3
 - PIND - method 2020, condition A, B
 - X-Ray Radiographic - method 2012
 - Centrifuge - method 2001
 - Temp cycle - method 101
 - Mechanical shock variable vibration - method 2007
 - Thermal vacuum testing

PLAINVIEW, NEW YORK
Toll Free: 800-THE-1553

SE AND MID-ATLANTIC
Tel: 321-951-4164
Fax: 321-951-4254

INTERNATIONAL
Tel: 805-778-9229
Fax: 805-778-1980

WEST COAST
Tel: 949-362-2260
Fax: 949-362-2266

NORTHEAST
Tel: 603-888-3975
Fax: 603-888-4585

CENTRAL
Tel: 719-594-8017
Fax: 719-594-8468

www.aeroflex.com info-ams@aeroflex.com

Aeroflex Microelectronic Solutions reserves the right to change at any time without notice the specifications, design, function, or form of its products described herein. All parameters must be validated for each customer's application by engineering. No liability is assumed as a result of use of this product. No patent licenses are implied.



Our passion for performance is defined by three attributes represented by these three icons: solution-minded, performance-driven and customer-focused